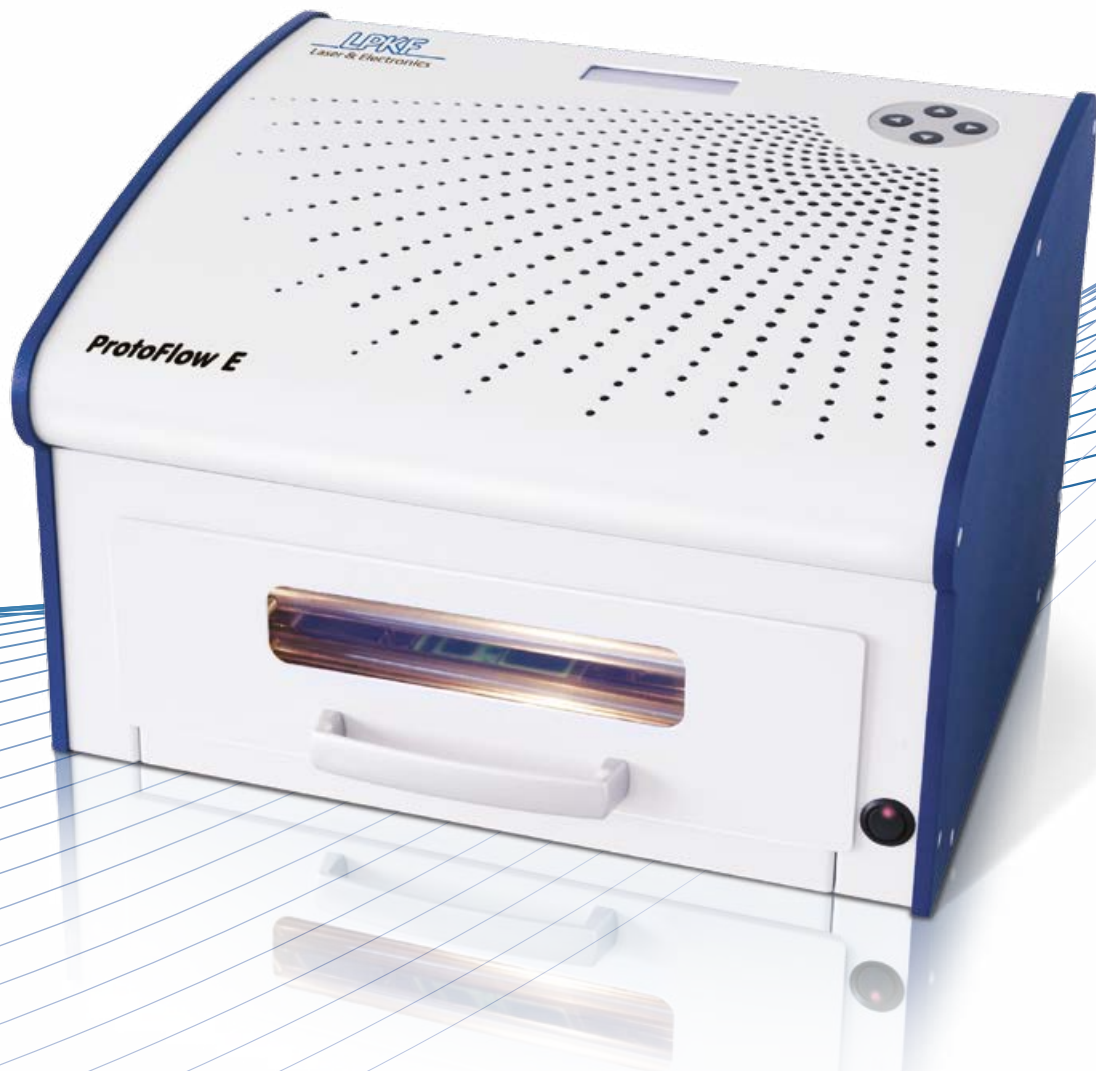


# Economical Convection Oven for SMT Prototyping

## LPKF ProtoFlow E

- Fully convectional
- Lead-free reflow process
- Temperature up to 320 °C
- Multi-zone temperature/time profiles
- USB connectivity



# Economical Solution for SMT Prototyping

The LPKF ProtoFlow E convection oven offers reliable reflow soldering across the entire PCB, including lead-free solder materials.

To provide a reliable connection between SMD components and the PCB circuitry, soldering by solder paste deposits is the common technology. The LPKF ProtoFlow E is a very economical and easy-to-use solution for reflow soldering PCBs.

Its temperature limit isn't reached until 320 °C (608 °F). The reflow oven with a max. material size of 160 mm x 200 mm (6.3" x 8") is perfectly matched to the LPKF ProtoPrint E.

A drawer window offers a view of the lighted process chamber, and the USB connection allows the LPKF ProtoFlow E to also be programmed from a PC for faster and easier process analysis.



	LPKF ProtoFlow E
<b>Max. PCB size</b>	160 mm x 200 mm (6.3" x 8")
<b>Max. preheat temperature/time</b>	220 °C (428 °F), 999 s
<b>Max. reflow temperature/time</b>	320 °C (608 °F), 600 s
<b>Long thermal treatment: temperature/time</b>	220 °C (428 °F), 64 h
<b>Temperature stabilizing time</b>	<5 min
<b>Power supply</b>	Single-phase 220 – 240 V, 50 – 60 Hz, 1650 W (max.)
<b>Dimensions (W x H x D)</b>	400 mm x 280 mm x 380 mm (15.7" x 11" x 14.7")
<b>Weight</b>	18 kg (40 lbs)

